

(1.27 mm) .050"

DWM-20-58-G-S-427

HDWM-24-59-L-S-300-SM

HDWM-08-56-L-D-312-SM

DWM-06-54-G-D-360

DWM, HDWM SERIES

MICRO BOARD STACKER

SPECIFICATIONS

For complete specifications see www.samtec.com?DWM or www.samtec.com?HDWM

Insulator Material:

LCP

Terminal Material:

Phosphor Bronze

Plating:

Au or Sn over

50 μ " (1.27 μ m) Ni

Operating Temp Range:

-55 °C to +105 °C with Tin

-55 °C to +125 °C with Gold

RoHS Compliant:

Yes

Mates with:

SMS, SLM, RSM

PROCESSING

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0.15 mm) .006" max*

*(.004" stencil solution may be available; contact IPG@samtec.com)

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



FILE NO. E111594

TYPE STRIP	NO. PINS PER ROW	LEAD STYLE	PLATING OPTION	ROW OPTION	STACKER HEIGHT	OTHER OPTION
	01 thru 50	Specify LEAD STYLE from chart	-L = 10 μ " (0.25 μ m) Gold contact, Matte Tin on tail -G = 10 μ " (0.25 μ m) Gold on post, Gold flash on tail	-S = Single Row -D = Double Row	-"XXX" = Stacker Height Example: -250 = (6.35 mm) .250"	-"XXX" = Polarized Position (Specify position of omitted pin) -SM = Surface Mount (Requires HDWM. 02 thru 40 positions only.) -A = Alignment Pin (Requires HDWM. 6 positions min -D only.) Metal or plastic at Samtec discretion (N/A with -LC) -LC = Locking Clip (Requires HDWM. 5 positions min. -D only) (N/A with -A) (Manual placement required) -P = Pick & Place Pad (Requires HDWM)

ALSO AVAILABLE (MOQ Required)

- Other platings

Notes:
For added mechanical stability, Samtec recommends mechanical board spacers be used in applications with gold or selective gold plated connectors. Contact ipg@samtec.com for more information.

This Series is non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

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All parts within this catalog are built to Samtec's specifications.

Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.